Product Roadmap

2026 Q2

ARK-I 2I640PW+ DM003

ROCK 2I130HW

SealPro - 2I130HW

SealPro - 3I140HW

TERA M12

HAWK 3I130TW

RUGGED EMBEDDED SYSTEM

Harsh Environments and
Mission-Critical Application

MIL-STD-810G Certified

EXTREME TEMP

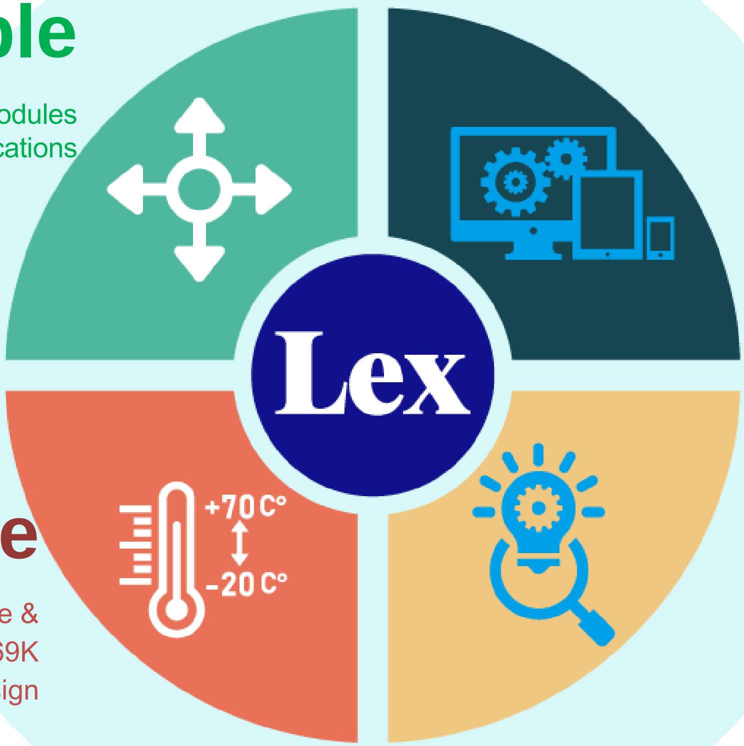
Anti Vibration

SHOCK &VIBRATION RESISTANT

Lex SYSTEM®

Contents

Features & Advantages



Flexible

Diverse Expansion interfaces and modules
for various Vertical Applications

Integrated

Accelerating Customer Development Speed
for Cross-Platform products

Stable

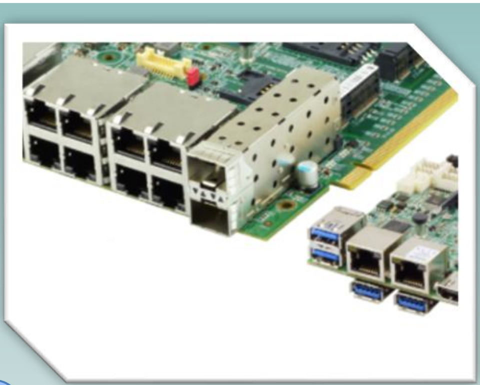
Wide Temperature, Wide Voltage &
Shock Resistance, IP66/IP67 & IP69K
Waterproof Design

Innovation

Fanless small Form Factor
Embedded tailored products or
space-constrained solutions

LEX SYSTEM – Embedded Solution

LEX offers design and manufacturing of industrial motherboards, industrial computers, expansion boards, and customized industrial computers, including edge computing systems and AI intelligent application platforms. Our in-house developed products cover four major categories:



1 Embedded IPC Board

- Single Board Computer
- CPU board
- Computer On Module
- UPS board
- ARM-based SBC

2 Customized Motherboard & Chassis

Innovating Research & Integration Services for Global OEM/ODM and System Integrators

- Applications

Smart Manufacturing / Machine Vision

AI / Visual Analytics

Smart Healthcare/ AI Medical Imaging

IoT / IIoT

Smart Transportation & Railways

Maritime Shipping & Navigation

Networking/ Communication Equipment

Edge Computing
Edge Gateway Control

Defense / Military Robust Computers

LEX SYSTEM – Embedded Solution

3 Fanless Rugged Panel PC,
Fanless Embedded Systems, Servers

4 Expansion Boards/Cards &
Related Accessories

Fanless Rugged Panel PC

- **SUPER series** (7”/10.1”/10.4”/15”)
- **VITA series** (10.1”/15”/21.5”/23.8”)
- Slim series (8.4”/10.2”/15.1”/17”)
- SHARK IP66/67 **waterproof** (10.1”/13.3”)
- STAR IP66/67 **waterproof** (10.4”/12.1”15.1”)
- **Stainless** IP66/IP67/IP69K **waterproof**

  (10.4”/15.1”/19”)

Fanless Embedded System

- Rugged /Waterproof System
- In-vehicle System
- DIN Rail System
- 1U server
- AI image Analysis & Machine Vision
- Ultra Compact / Compact System

- High-Speed Ethernet Network Card / PoE / Fiber Card
- 4G / 5G / WiFi / Bluetooth Module
- Video Capture Car
- USB / SIM / COM / Display Conversion Card
- M.2 / eIO Expansion Card
- Storage Card
- Digital IO Card
- Carriers and Converter Boards
- Power Boards and Charger Modules

Embedded Solution– Case Study

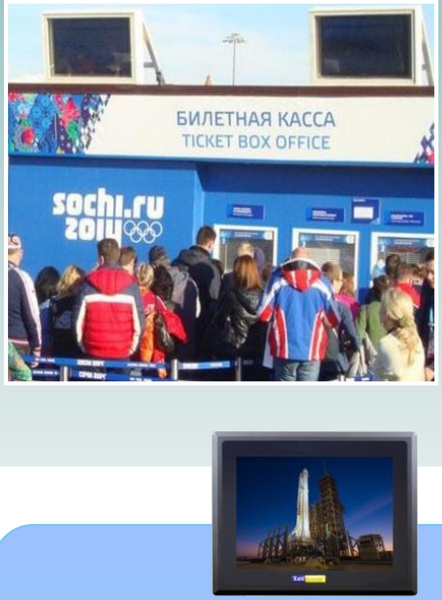
Spain
Intelligent Transportation
Surveillance System

China
Highway ETC smarting
billing system

Germany
3D Surgery Navigation

China
Servortronix EtherCAT
Robot Motion Control

Embedded Solution– Case Study



Kiosk-Self Service
Harsh outdoor Panel PC
for Winter Olympics

Video Analysis
Metro Real-time
Surveillance System

Poland
Railway in-train
communication

Netherlands
Fleet management

2026 Q2 Product Highlights

3I160DW-3.5” SBC

Intel® Core™ Ultra CPU
(Panther Lake)
2 x HDMI ®, LVDS/eDP, 1 X Type C
2 x DDR5 SODIMM Max 96 GB
5 x Intel 2.5 GbE, 3 x USB 3.2, 5 x USB 2.0
3 x M.2 ,1 x Nano SIM ,1 x PCIex2, 2 x PCIex4
HD Audio , 3 x MIPI-CSI, 4 x COM, 4DI / 4DO

2I140D-2.5” SBC

Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
HDMI ®, eDP
Onboard LPDDR5 16 / 32GB
4 x Intel 2.5 GbE, 3 x USB 3.2, 4 x USB 2.0
2 x M.2 ,1 x Nano SIM, 2 x COM, 4DI / 4DO

3I140HW-3.5” SBC

Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
DP, HDMI ®, LVDS /DP
2 x DDR5 SODIMM Max 64GB
3 x Intel 2.5 GbE, 4 x USB 3.2, 3 x USB 2.0
3 x M.2 ,1 x Nano SIM, HD Audio
4 x COM, 4DI / 4DO ,2 X MIPI-CSI

2I132DW-2.5” SBC

Intel® 13th Gen Raptor Lake-U CPU
Onboard LPDDR5 ,16 /32GB
HDMI ®, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2 , 1 x Nano SIM

2I740DW-2.5” SBC

Intel® ATOM Amston Lake x7000 CPU
Onboard LPDDR5, Max 32GB
1 x HDMI®
3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2 , 2 x COM

2I740CW-2.5” SBC

Intel® ATOM Amston Lake x7000 CPU
1 x SODIMM DDR5, Max 16GB
HDMI®, Type C , LVDS
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB 3.2 Type C,2 x M.2 , 1 x Nano SIM
2 x MIPI-CSI, 4 x COM, 4DI/4DO

2I740AW-2.5” SBC

Intel® ATOM Amston Lake x7000 CPU
1 x SODIMM DDR5, Max 16GB
HDMI®, 1 x Intel 2.5 GbE, 4 x COM
4 x USB 3.2, 2 x USB 2.0
2 x M.2 , 1 x MINI SIM,

2I642DW-2.5” SBC

Intel® ATOM
Elkhart Lake x6413E / J6412 CPU
Onboard LPDDR5, 16 /32GB
2 x HDMI®, eDP 3 x Intel 2.5 GbE
2 x USB 3.0, 3 x USB 2.0
2 x M.2 , 1 x Nano SIM,

Product Highlights（ Embedded IPC Board ）

intel Core 13th Gen Raptor Lake

2I130HW-2.5” Plus SBC
2I130DW-2.5” Plus SBC
3I130DW-3.5” Plus SBC
3I130TW-161x150 mm SBC

intel Core 11th Gen Tiger Lake-UP3

2I110D-2.5” Plus SBC
2I110AW-2.5” Plus SBC
3I110HW/BW-3.5” Plus SBC

intel Core 10th Gen Comet Lake-S

3I470DW-155 x150 mm SBC

intel Core 9 th Gen Coffee Lake-S
intel Core 8 th Gen Coffee Lake-S

CI370D-217 x 185 mm SBC
CI371D-217 x 223 mm SBC
3I370DW-155 x130 mm SBC

intel Core 8 th Gen Whiskey Lake-U

2I810D-2.5” Plus SBC
3I810DW-3.5” Plus SBC
3I810HW/BW-3.5” Plus SBC

intel Elkhart Lake
intel Atom

2I640PW-Compute on Module
2I640HL-2.5”Plus SBC with Hailo-8
2I640DW-2.5”Plus SBC
2I640CW-2.5”Plus SBC
2I640HW-2.5”Plus SBC
2I640SW-2.5”Plus SBC
3I640DW-3.5” SBC
3I640CW-3.5” SBC

NVIDIA.

2NOR01- 2.5” Plus carrier board
For Board for Edge AiI solution with
NVIDIA® Jetson Orin™ Nano (Super)NX

ORIN-TW
Carrier Board for Railway solution with
NVIDIA® Jetson Orin™ Nano(Super) / NX

2NOR02- compact carrier board
For Edge AiI solution with NVIDIA® Jetson
Orin™ Nano / NX

2NOR03- compact carrier board
For Edge AiI solution with NVIDIA® Jetson
Orin™ Nano / NX

NXP

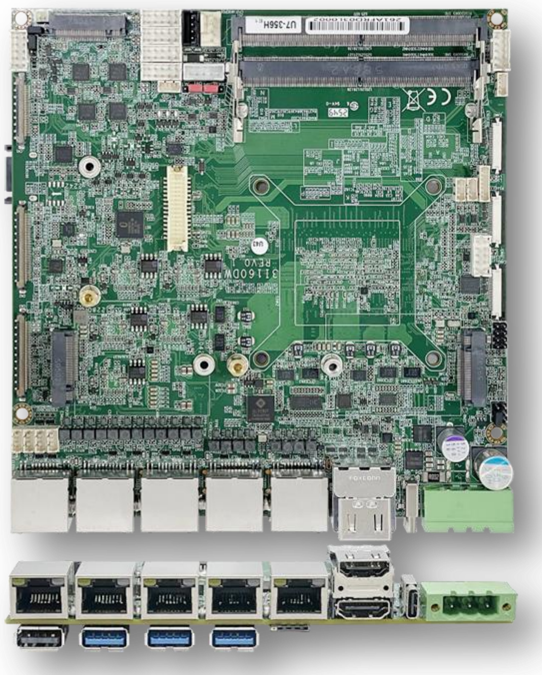
2N8MP01- 2.5” Plus SBC

NXP-HAI02- -carrier board with Hailo AI chip
For Edge AiI solution with I.MX8M Plus CPU

NXP-HAI03 -carrier board with Hailo AI chip
For Edge AiI solution with I.MX8M Plus CPU

2026 Q2 Product Development timeline

Intel® Core™ Ultra CPU (Series 3)



3I160DW

Intel® Core™ Ultra 300 Series (Panther Lake) processors

Revamped I GPU and integrated NPU

2 x DDR5 SODIMM, Max 96GB

Multiple Independent display: 2 x HDMI®, LVDS / eDP, 1 x Type C

5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen1x1, 5 x USB 2.0,

1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM,

1 x PCIe x2, 2 x PCIe x 4

4 x COM, 4DI / 4DO, 3 x MIPI-CSI, HD Audio

TPM 2.0, SMBus, I2C, I2S

Dimension: 146 x 150 mm

2026 Q2 Product Development timeline

Intel® Core™ Ultra CPU

intel Core Ultra Meteor Lake

intel Core Ultra Arrow Lake

2I140D

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
On board LPDDR5 16/32 GB
1 x HDMI®,eDP,
4 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 1 x M.2 B Key, 1 x Nano SIM
2 x COM, 4DI / 4DO, Audio (OEM)
TPM 2.0, SMBus, I2C, DC IN+ 12V
Dimension: 108 x 112 mm

3I140DW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, 1 x DP, LVDS, 1 x Type C
5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe
4 x COM, 2 x CANBus , 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, I2S ,Wide Range DC IN+9~36V
Dimension: 150 x 155 mm

HAWK 3I140DW

3I140HW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, LVDS, 1 x Type C
3 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, High Speed Connector (PCIe x2)
4 x COM, 2 x MIPI-CSI, 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, Wide Range DC IN+9~36V
Dimension: 146 x 150 mm

IP66 IP67 Waterproof

SealPro 3 3I140HW

2026 Q2 Product Development timeline

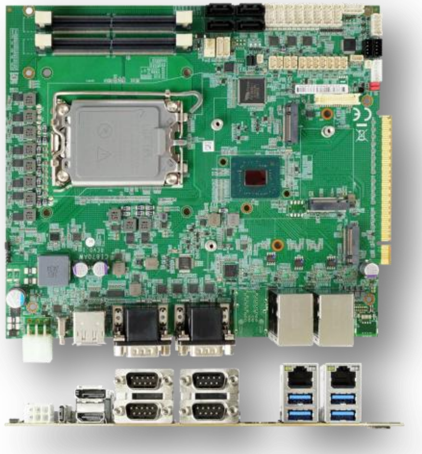
Intel® Core™ Ultra CPU

CI870CW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 96 GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x eDP / LVDS, 1 x Type C
5 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
10 x COM, 8DI / 8DO, Audio
TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)

TWISTER(L)-CI870AW

TWISTER(L)-CI870CW



CI870AW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 96GB
Multiple Independent display:
1 x HDMI®, 1 x DP,1 x Type C
2 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 8DI / 8DO, TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)

1U Fanless-CI870AW

1U Fanless-CI870CW

2026 Q2 Product Development timeline

13th Gen Intel® Core™ Raptor Lake-P/U

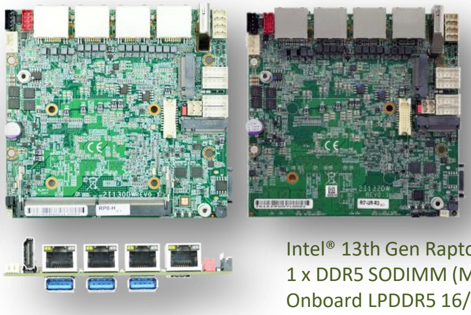
2I130HW

Intel® 13th Gen Raptor Lake-U/P CPU
1 x DDR5 SODIMM (Max. 32GB)
HDMI ®, eDP, LVDS
2 x Intel 2.5 GbE, 4 x USB 3.2
4 x USB 2.0 2 x COM, 4DI / 4DO,
HD Audio ,1 x Mini PCIe, 1 x M.2
108 x 102 mm

ROCK 2I130HW

IP66 IP67 Waterproof

SealPro 2I130HW



2I130DW / 2I132DW

Intel® 13th Gen Raptor Lake-U CPU
1 x DDR5 SODIMM (Max. 32GB) -2I130DW
Onboard LPDDR5 16/ 32GB-2I132DW
HDMI ®, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2 , 1 x Nano SIM
108 x 102/ 108 x 105 mm

FOX 2I130DW

SKY 2 2I130DW

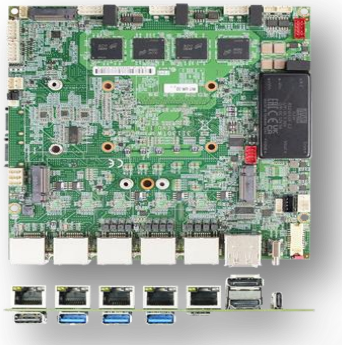
ROCK 2I130DW

3I130DW

Intel® 13th Gen Raptor Lake-P / U CPU
2 x DDR5 SODIMM (Max. 64GB)
2 x HDMI ®,eDP , 1 x Type C DP ALT Mode
5 x Intel 2.5 GbE, 3 x USB 3.2, 5x USB 2.0
1 x Mini PCIe, 2 x M.2 ,1 x Nano SIM
2 x COM, 4DI / 4DO
146 x 110 mm

HAWK 3I130DW

SKY 3 3I130DW



3I130TW

Intel® 13th Gen Raptor Lake- U CPU
On-board LPDDR5 (16GB/32 GB)
HDMI ®,DP, eDP ,5 x Intel 2.5 GbE,
3 x USB 3.2, 3x USB 2.0, 3 x M.2 ,
1 x Nano SIM ,2 x ISO-COM, HD Audio
2 x ISO- CANBus, 4DI / 4DO , onboard NVMe
CPC –Ignition Delay on/off control
161 x 150 mm

EN50155

HAWK 3I130TW (M12)

Mobile Rack (Optional)

2026 Q2 Product Development timeline

NVIDIA Jetson Orin Nano(Super)/ NX SOM Carrier Board

CPU Board:
NVIDIA Jetson NX: 8 / 16GB LPDDR5, 70 / 100 TOPs
NVIDIA Jetson Nano(Super): 4 / 8GB LPDDR5, 20 / 40 TOPs
AI Accelerator: NVIDIA® Jetson Orin™ Nano(Super) / Orin™ NX

2NOR02

1 x HDMI®, 1 x GbE
8 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
1 x RS232 (OEM to RS422)
1 x M.2 M key, 1 x M.2 B key,
URAT, I2S, 2 x I2C

FOX 2NOR02

2NOR03

1 x HDMI ®, 1 x GbE, 1 x 2.5GbE
2 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG)
1 x RS232 (OEM Option RS422)
1 x M.2 M key, 1 x M.2 B key
Support **8 X GMSL cameras**

FOX 2NOR03+GM04

ORIN-TW

1 x DP, 5 x GbE (1 + 4 x PoE)
1 x USB 3.1 Type C ; 2 x USB 3.1 Type A ; 1x USB 2.0
Mic-in / Line-out ; AMP 2W, 2 x SATA
2 x Isolated RS232 / RS422 / RS485, 1 x Isolated CANBus
1 x M.2 M key, 4 x M.2 B key, 1 x M.2 E Key, 1 x Nano SIM
2 x MIPI CSI, SPI, I²S, 3 x I²C,8DI / 8 DO,
ISO Wide Range +9~36V, CPC-Ignition on/off delay control

HAWK ORIN-TW
M12 I/O / Mobile Rack (Optional)

2NOR01

1 x HDMI®, , 2 x 2.5GbE, 1 x GbE
4 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
Mic-in / Line-out ; AMP 2W
2 x RS232 (Option RS422), 1 x CANBus
1 x M.2 M key 2 x M.2 B key, 1 x SIM, 4DI / 4DO
Internal wafer: SPI, I2S, I2C, USB 2.0

SKY 2 2NOR01

ROCK 2NOR01

2026 Q2 Product Development timeline

NXP i.MX8M Plus /ARM Cortex-A53

2N8MP01

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 + M7 CPU
LPDDR4, 4GB / 8GB
Independent display: 1 x HDMI ®, LVDS,
3 x GbE LAN, 2 x USB 3.0, 3 x USB 2.0
2 x COM, 3 x M.2, 1 x Nano SIM, 1 x Type C USB 3.0 (OTG)
4DI / 4DO,1 x MIPI (CSI),1 x CANBus
115.4 x 84.5 mm

NET-II 2N8MP01

PALM-NEX001

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 CPU
LPDDR4, 8GB (NEX-8MP)
32GB eMMC 5.1 (NEX-8MP),
expandable to 256GB
HDMI ® ; 2 x GbE ; 2 x USB 3.0 / 2.0
1 x Micro SD, 1 x RS232, 1 x RS485
DC input : +5V
71.4W x 71.4D x 29.5H mm

Ultra Compact solution with Onboard Hailo-8™ AI processor

EMPOWERED BY HAILO

NXP-HAI02 / HAI03

NXP i.MX8M Plus (Quad core) ARM Cortex-A53 CPU
LPDDR4, 8GB (NEX-8MP),32-256GB eMMC 5.1 (NEX-8MP)
Mini HDMI ®, 1 x USB 3.0 Type C,1 x GbE(M12) or 2 x RJ45 ;
1 x USB 3.0 Type A, 1 x Micro SD,
M8 Connector: DC Power, LAN, DI/DO ,RS485
Wide Range DC-IN +9-24V
Dimension: 66W x 94D x 30.8H mm

NXP-HAI02

NXP-HAI03

With NEX-8MP computer on module

MINI NXP-HAI02

MINI NXP-HAI03

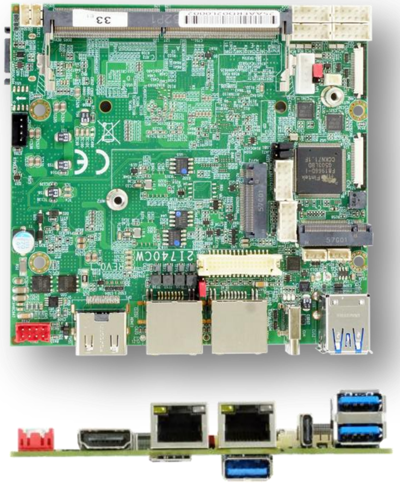
2026 Q2 Product Development timeline

Intel® Amston Lake ATOM x7000 series processor

2I740DW

Intel® ATOM Amston Lake x7000 series CPU
Onboard LPDDR5, Max 32GB
HDMI® ,3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2 , 1 x Nano SIM, 2 x COM,
Wide Range DC-IN +9~24V
115.4 x 84.5 mm

NET-II 2I740DW



2I740CW

Intel® ATOM Amston Lake x7000 series CPU
1 x DDR5 SODIMM, Max. 16GB
HDMI®, Type C ALT, LVDS
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB3.2 Type C , 2 x MIPI-CSI, 4DI/4DO
2 x M.2 , 4 x COM, Wide Range DC-IN +9~36V
108 x 102 mm

LEX Sereies Pancel PC

2026 Q2 Product Development timeline

Expansion Card and Modules

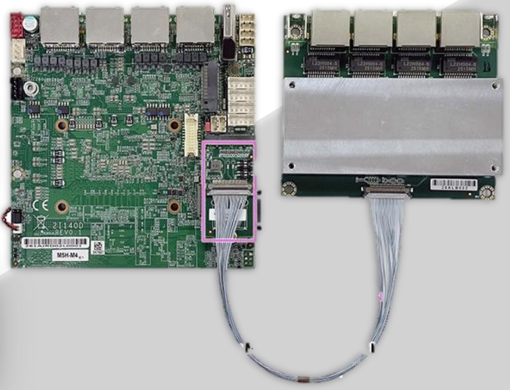
CN073 / CN075

M.2 B+M Key2242 /2280 connector board
Via USB3.2 Type A / USB 3.2 SSL / PCIe

CU006
1 x USB convert to 4 x USB 3.0 HUB

CL210A
4 Port GbE LAN board

CL210P
4 Port PoE GbE LAN



Easy Expansion:
Connect the set to the SBC's M.2 B+M slot to
enable 4 x GbE LAN / 4 x PoE LAN / 4 x USB 3.0

PW505
Isolation power board
with CPC-Ignition on/off control
1.5KVDC I/O isolation
PW505-36: 9–36V in, 12V out, max 60W
PW505-75: 18–75V in, 12V out, max 60W

CC107

USB to 4 x ISO RS232/422/485

M504B

Mini PCIe to 4* RS232/485/422
(F81504U)

ADC002
Analog Input solution

LEX SYSTEM with Long-Term Supply

EOL Timeline	2028	2029	2030	2031	2032	2033	2034	2035	2036
Bay Trail	Q4								
Apollo Lake				Q3					
Elkhart Lake				Q1					
Amston Lake							Q2		
Skylake 6th	2026 Q2								
Kaby Lake 7th					Q1				
Coffee Lake 8th						Q2			
Coffee Lake 9th							Q2		
Whisky Lake						Q3			
Comet Lake			Q2						
Tiger Lake UP3			Q3						
Raptor Lake						Q1			
Meteor Lake-U/H						Q4			
Arrow Lake-U			Q1						
Arrow Lake-S			Q1						
Panther Lake									Q1
Nova Lake									Q1
i.MAX 8M Plus								Q1	
Jetson Orin Nano NX			Q1						

* Product life span in alignment with Intel's IOTG / NVIDIA modules Life cycle /NXP CPU longevity.

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